

## AMENDMENTS TO THE SPECIFICATION

Please amend Paragraphs [0002], [0007], [0089] and [0099] of the specification as follows:

[0002] This application is also related to copending Application Serial No. 09/349,806, filed July 8, 1999, Publication No. 2002/0113770.

[0007] Numerous patents and applications assigned to or in the names of the Massachusetts Institute of Technology (MIT) and E Ink Corporation have recently been published describing encapsulated electrophoretic media. Such encapsulated media comprise numerous small capsules, each of which itself comprises an internal phase containing electrophoretically-mobile particles suspended in a liquid suspending medium, and a capsule wall surrounding the internal phase. Typically, the capsules are themselves held within a polymeric binder to form a coherent layer positioned between two electrodes. Encapsulated media of this type are described, for example, in U.S. Patents Nos. 5,930,026; 5,961,804; 6,017,584; 6,067,185; 6,118,426; 6,120,588; 6,120,839; 6,124,851; 6,130,773; 6,130,774; 6,172,798; 6,177,921; 6,232,950; [[6,249,721]]6,249,721; 6,252,564; 6,262,706; 6,262,833; 6,300,932; 6,312,304; 6,312,971; 6,323,989; 6,327,072; 6,376,828; 6,377,387; 6,392,785; 6,392,786; 6,413,790; 6,422,687; 6,445,374; 6,445,489; 6,459,418; 6,473,072; 6,480,182; 6,498,114; 6,504,524; 6,506,438; 6,512,354; 6,515,649; 6,518,949; 6,521,489; 6,531,997; 6,535,197; 6,538,801; 6,545,291; 6,580,545; 6,639,578; 6,652,075; 6,657,772; 6,664,944; 6,680,725; 6,683,333; and 6,704,133; and U.S. Patent Applications Publication Nos. 2002/0019081; 2002/0021270; 2002/0053900; 2002/0060321; 2002/0063661; 2002/0063677; 2002/0090980; 2002/0106847; 2002/0113770; 2002/0130832; 2002/0131147; 2002/0145792; 2002/0171910; 2002/0180687; 2002/0180688; 2002/0185378; 2003/0011560; 2003/0011868; 2003/0020844; 2003/0025855; 2003/0034949; 2003/0038755; 2003/0053189; 2003/0096113; 2003/0102858; 2003/0132908; 2003/0137521; 2003/0137717; 2003/0151702; 2003/0189749; 2003/0214695; 2003/0214697; 2003/0222315; 2004/0008398; 2004/0012839; 2004/0014265; and

2004/0027327; and International Applications Publication Nos. WO 99/67678; WO 00/05704; WO 00/38000; WO 00/38001; WO00/36560; WO 00/67110; WO 00/67327; WO 01/07961; WO 01/08241; WO 03/092077; and WO 03/107,315.

[0089] Furthermore, as discussed in the aforementioned [[2004/0027326]]2004/0027327, for commercial reasons it is advantageous to form, after capsule deposition, a so-called "front plane laminate" comprising, in order, a light-transmissive electrically-conductive layer, a layer of an electro-optic medium in electrical contact with the electrically-conductive layer, an adhesive layer and a release sheet. Such a front plane laminate can be prepared as a continuous web, cut to size, the release sheet removed and the laminate laminated to a backplane to form a display. Obviously, such a front plane laminate requires that the capsules be deposited upon a continuous front electrode, and hence such a front plane laminate cannot be prepared by the type of multi-step capsule deposition process described above, which deposits the capsules on discrete sets of pixel electrodes.

[0099] As already mentioned, the principal advantage of processes of the present invention similar to those described with reference to Figures 3A-3D and 4A-4F is that they enable electrophoretic deposition of patterned capsule/binder layers on to a continuous top plane (front) electrode, and such deposition offers significant electro-optical and appearance advantages over similar patterned deposition on to backplane electrodes. Although patterned deposition on to a top plane electrode ultimately requires alignment of the patterned layer with the backplane addressing (pixel) electrodes, this alignment step is similar to that commonly used in assembling color liquid crystal displays and is therefore well understood. Although deposition directly on to the backplane electrodes avoids an alignment step, the backplane transistor array in an active matrix display is one of more expensive components of the display and any defects in the coating process would require scrapping or reworking of the backplane. In addition, deposition on to the backplane electrode is fundamentally a batch process, while even high resolution patterned deposition on a front plane electrode appears amenable to use of

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high volume continuous processes, for example on a roll-to-roll basis, in a manner similar to the processes for the preparation of front plane laminates described in the aforementioned [[2004/0027326]]2004/0027327.